

RULE 202. EXEMPTIONS TO RULE 201. (Adopted 10/18/1971, revised 5/1/1972 and 6/27/1977, readopted 10/23/1978, revised 12/7/1987, 1/11/1988, 1/17/1989, 7/10/1990, 7/30/1991, 11/05/1991, 3/10/1992, 5/10/1994, 6/28/1994, 4/17/1997, 3/17/2005, 1/17/2008, 6/19/2008, and 9/20/2010, and [date of amended rule adoption])

[...]

D. General Provisions

[...]

7. Stationary Source Permit Exemption

A permit shall not be required for any new, modified or existing stationary source if the uncontrolled actual emissions of each individual affected pollutant from the entire stationary source are below 1.00 ton per calendar year, unless:

[...]

e. the source is a new or modified source which emits hazardous air emissions and is located within 1,000 feet from the outer boundary of a school site (Health and Safety Code Section 42301.6, *et seq.*); or

f. the source is subject to a California Air Resources Board rule or regulation adopted pursuant to the California Global Warming Solutions Act of 2006 (Health and Safety Code Section 38500, *et seq.*).

[...]

12. Emission control equipment, directly attached to equipment which is exempt from permit by provisions of this ~~Rule~~rule, is exempt to Operate are fully complied with.

[...]

E. Compliance with Rule Changes

The provisions of this section shall apply when an exemption for existing equipment is removed by revision of this ~~Rule~~rule.

[...]

T. Semiconductor and Electronics Manufacturing Equipment and Operations

The following semiconductor and electronics manufacturing equipment and operations is exempt from permit requirements. Notwithstanding the listed exemptions, any collection of articles, machines, equipment or other contrivances within each listed equipment category at a stationary source that has aggregate emissions in excess of one ton per calendar year of any affected pollutant is not exempt.

Notwithstanding the listed exemptions, any article, machine, equipment or other contrivance that utilizes or creates fluorinated gas(es) is not exempt.

1. Vacuum deposition.
2. Ion implantation.
3. Sputtering.

4. Ozone/plasma/ion etching or ashing.
5. Vacuum bake systems.
6. Furnaces used for crystal growth, liquid phase epitaxial, compounding and/or refining, and carbon coating.
7. Automated epoxy adhesive, potting compound, conformal coating dispensing machines and associated equipment used for mixing, injection and curing.
8. Ovens used exclusively for curing epoxies and adhesives. Ovens used exclusively for curing permitted paint application processes.
9. Ovens for drying parts cleaned with water.

[...]

V. Storage and Transfer Equipment and Operations

The following storage and transfer equipment and operations ~~is~~are exempt from permit requirements.

[...]